imall

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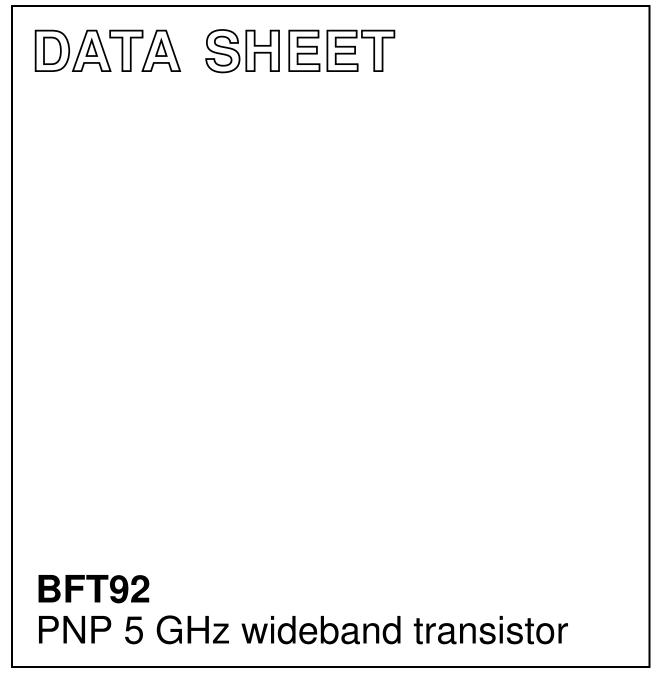


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DISCRETE SEMICONDUCTORS



Product specification

November 1992



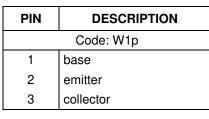
DESCRIPTION

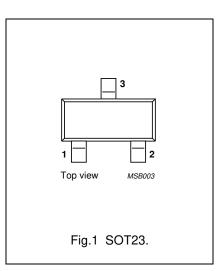
PNP transistor in a plastic SOT23 envelope.

It is primarily intended for use in RF wideband amplifiers, such as in aerial amplifiers, radar systems, oscilloscopes, spectrum analyzers, etc. The transistor features low intermodulation distortion and high power gain; due to its very high transition frequency, it also has excellent wideband properties and low noise up to high frequencies.

NPN complements are BFR92 and BFR92A.

PINNING





QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	-20	V
V _{CEO}	collector-emitter voltage	open base	_	-15	V
I _C	DC collector current		-	-25	mA
P _{tot}	total power dissipation	up to T _s = 95 °C; note 1	_	300	mW
f _T	transition frequency	$I_{C} = -14 \text{ mA}; V_{CE} = -10 \text{ V}; f = 500 \text{ MHz}$	5	-	GHz
C _{re}	feedback capacitance	$I_{C} = -2 \text{ mA}; V_{CE} = -10 \text{ V}; f = 1 \text{ MHz}$	0.7	-	pF
G _{UM}	maximum unilateral power gain	$I_{C} = -14 \text{ mA}; V_{CE} = -10 \text{ V};$ f = 500 MHz; T _{amb} = 25 °C	18	_	dB
F	noise figure	$I_{C} = -5 \text{ mA}; V_{CE} = -10 \text{ V}; f = 500 \text{ MHz};$ $T_{amb} = 25 \text{ °C}$	2.5	-	dB
d _{im}	intermodulation distortion	$ I_{C} = -14 \text{ mA}; \text{ V}_{CE} = -10 \text{ V}; \text{ R}_{L} = 75 \Omega; \\ V_{o} = 150 \text{ mV}; \text{ T}_{amb} = 25 \text{ °C}; \\ f_{(p+q-r)} = 493.25 \text{ MHz} $	-60	_	dB

Note

1. T_s is the temperature at the soldering point of the collector tab.

BFT92

LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	-20	V
V _{CEO}	collector-emitter voltage	open base	-	–15	V
V _{EBO}	emitter-base voltage	open collector	_	-2	V
I _C	DC collector current		_	-25	mA
I _{CM}	peak collector current 1	f > 1 MHz	-	-35	mA
P _{tot}	total power dissipation	up to T _s = 95 °C; note 1	_	300	mW
T _{stg}	storage temperature		-65	150	°C
Tj	junction temperature		-	175	°C

THERMAL RESISTANCE

SYMBOL	PARAMETER	CONDITIONS	THERMAL RESISTANCE		
R _{th j-s}	thermal resistance from junction to soldering point	up to T _s = 95 °C; note 1	260 K/W		

Note

1. T_s is the temperature at the soldering point of the collector tab.

BFT92

CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$ unless otherwise specified.

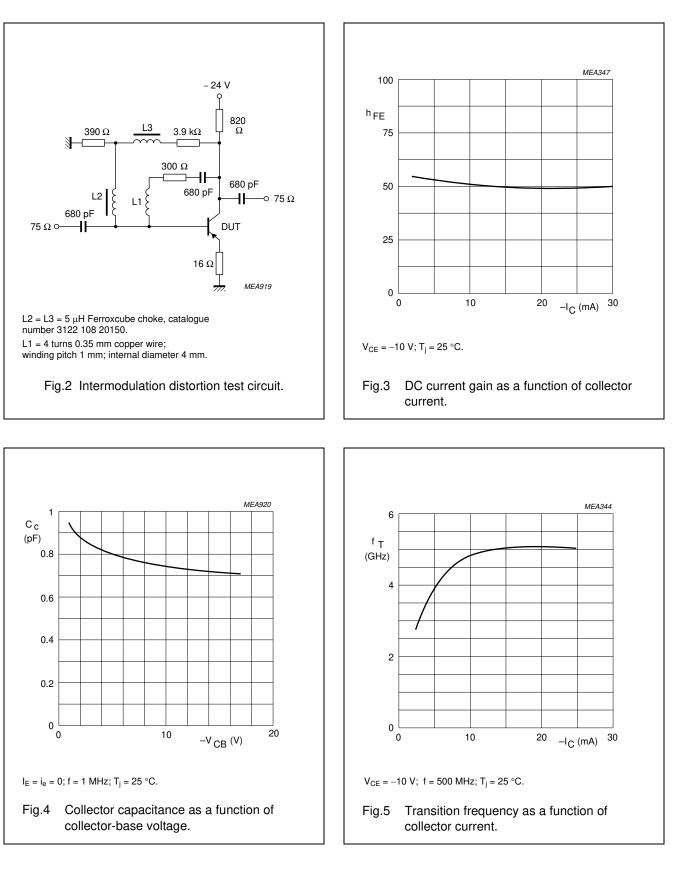
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector cut-off current	$I_{E} = 0; V_{CB} = -10 V;$	-	_	-50	nA
h _{FE}	DC current gain	$I_{C} = -14 \text{ mA}; V_{CE} = -10 \text{ V}$	20	50	-	
f _T	transition frequency	$I_{C} = -14 \text{ mA}; V_{CE} = -10 \text{ V};$ f = 500 MHz	-	5	-	GHz
C _c	collector capacitance	$I_E = i_e = 0; V_{CB} = -10 V; f = 1 MHz$	-	0.75	-	pF
C _e	emitter capacitance	$I_{C} = i_{c} = 0; V_{EB} = -0.5 V; f = 1 MHz$	-	0.8	-	pF
C _{re}	feedback capacitance	$I_{C} = -2 \text{ mA}; V_{CE} = -10 \text{ V}; f = 1 \text{ MHz}$	-	0.7	_	pF
G _{UM}	maximum unilateral power gain (note 1)	$I_{C} = -14 \text{ mA}; V_{CE} = -10 \text{ V};$ f = 500 MHz; T _{amb} = 25 °C	-	18	-	dB
F	noise figure	$I_{C} = -5 \text{ mA}; V_{CE} = -10 \text{ V};$ f = 500 MHz; T _{amb} = 25 °C	-	2.5	-	dB
Vo	output voltage	note 2	-	150	-	mV

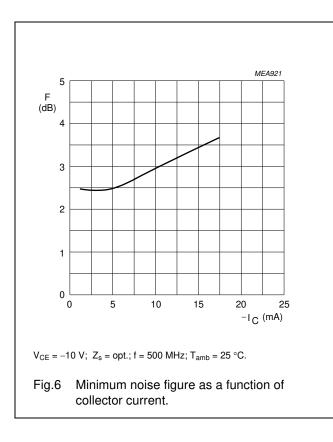
Notes

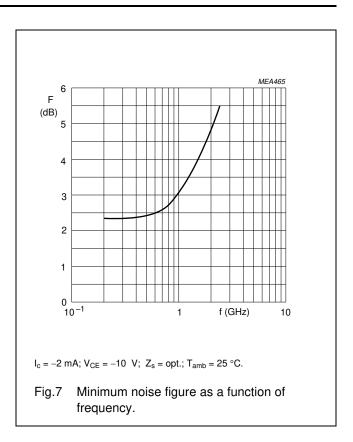
1. G_{UM} is the maximum unilateral power gain, assuming S_{12} is zero and

$$G_{UM} = 10 \log \frac{|S_{21}|^2}{(1 - |S_{11}|^2)(1 - |S_{22}|^2)} dB.$$

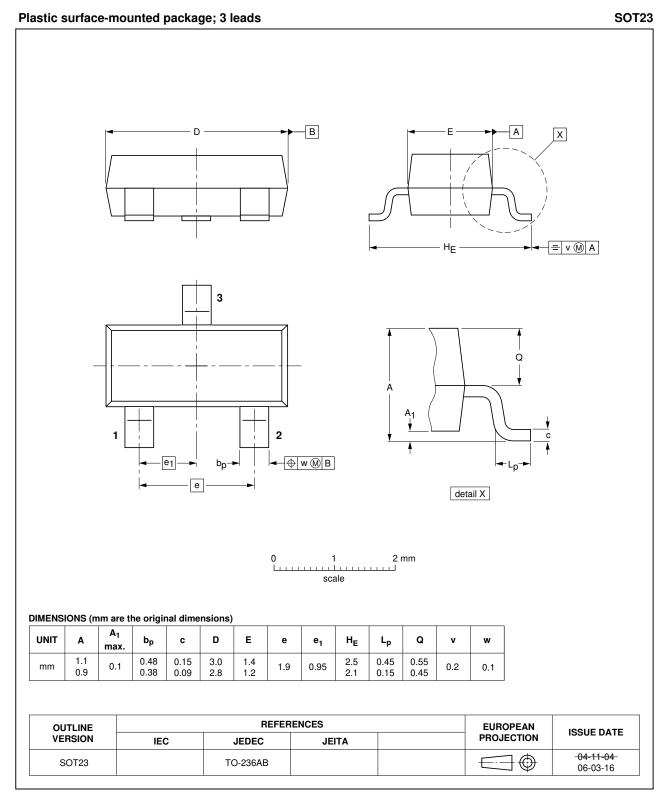
 $\begin{array}{ll} \text{2.} & d_{im} = -60 \; dB \; (\text{DIN } 45004B); \; I_C = -14 \; \text{mA}; \; V_{CE} = -10 \; V; \; R_L = 75 \; \Omega; \\ & V_p = V_o \; at \; d_{im} = -60 \; dB; \; f_p = 495.25 \; \text{MHz}; \\ & V_q = V_o \; -6 \; dB; \; f_q = 503.25 \; \text{MHz}; \\ & V_r = V_o \; -6 \; dB; \; f_r = 505.25 \; \text{MHz}; \\ & \text{measured at } f_{(p+q-r)} = 493.25 \; \text{MHz}. \end{array}$







PACKAGE OUTLINE



BFT92

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Contact information

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